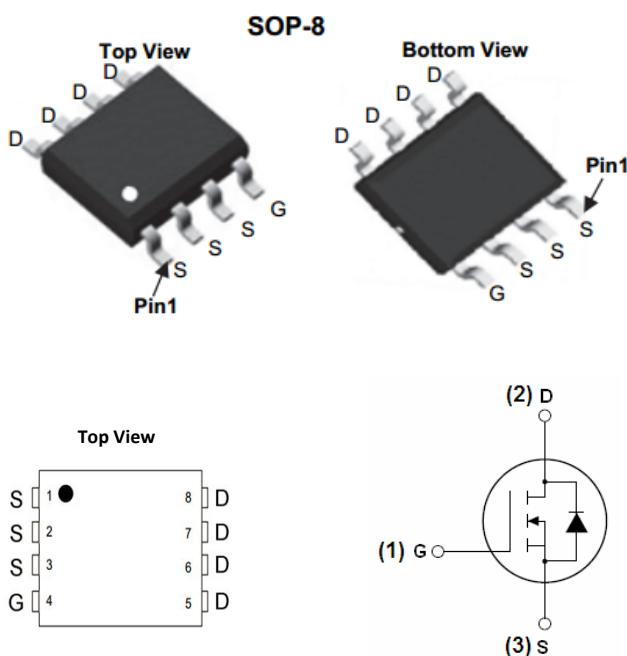


## N-Channel Enhancement Mode Field Effect Transistor



### Product Summary

• $V_{DS}$	60V
• $I_D$ (at $V_{GS}=10V$ )	12A
• $R_{DS(ON)}$ ( at $V_{GS}=10V$ )	<9.0mΩ
• $R_{DS(ON)}$ ( at $V_{GS}=4.5V$ )	<13.0mΩ
• 100% UIS Tested	
100% $R_g$ Tested	
100% $\nabla V_{DS}$ Tested	

### General Description

- Split Gate Trench Power MV MOSFET technology
- Low  $R_{DS(ON)}$
- Low Gate Charge
- Optimized for fast-switching applications

### Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive application

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter		Symbol	Maximum	Unit
Drain-source Voltage		$V_{DS}$	60	V
Gate-source Voltage		$V_{GS}$	$\pm 20$	V
Drain Current <sup>G</sup>	$T_C=25^\circ C$	$I_D$	12	A
	$T_C=100^\circ C$		9	
Pulsed Drain Current <sup>C</sup>		$I_{DM}$	48	A
Avalanche energy $L=0.5mH$ <sup>C</sup>		$E_{AS}$	195	mJ
Power Dissipation <sup>A</sup>	$T_C=25^\circ C$	$P_{DSM}$	3.1	W
	$T_C=100^\circ C$		2.0	
Junction and Storage Temperature Range		$T_J, T_{STG}$	-55~+150	°C

### Thermal Characteristics

Parameter		Symbol	Typ.	Max.	Unit
Junction-to-Ambient <sup>A</sup>	$T \leq 10s$	$R_{\theta JA}$	30	40	°C / W
	Steady-State		58	75	°C / W
Junction-to-Case		$R_{\theta JC}$	15	24	°C / W

### Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJS12G06A			4000			Tape & reel

■Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	65		V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
		$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}, T_J=55^\circ\text{C}$			5	
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.1	1.7	2.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=12\text{A}$		8.2	9.0	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=12\text{A}$		10.5	13.0	
Diode Forward Voltage	$\text{g}_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=12\text{A}$	30			S
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=12\text{A}, V_{\text{GS}}=0\text{V}$		0.83	0.99	V
Maximum Body-Diode Continuous Current <sup>G</sup>	$I_{\text{S}}$				12	A
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1988		$\text{pF}$
Output Capacitance	$C_{\text{oss}}$			470		
Reverse Transfer Capacitance	$C_{\text{rss}}$			14		
Gate Resistance	$R_g$	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1.6		$\Omega$
<b>Switching Parameters</b>						
Total Gate Charge	$Q_g(10\text{V})$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=30\text{V}, I_{\text{D}}=12\text{A}$		31		$\text{nC}$
Total Gate Charge	$Q_g(4.5\text{V})$			16		
Gate Source Charge	$Q_{\text{gs}}$			6		
Gate Drain Charge	$Q_{\text{gd}}$			5		
Turn-on Delay Time	$t_{\text{D}(\text{on})}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=15\text{V}, R_L=2.5\Omega, R_{\text{GEN}}=3\Omega$		10.5		$\text{ns}$
Turn-on Rise Time	$t_r$			4.5		
Turn-off Delay Time	$t_{\text{D}(\text{off})}$			29.5		
Turn-off Fall Time	$t_f$			8		
Body Diode Reverse Recovery Time	$t_{\text{rr}}$	$I_F=12\text{A}, di/dt=500\text{A/us}$		17		
Body Diode Reverse Recovery Charge	$Q_{\text{rr}}$	$I_F=12\text{A}, di/dt=500\text{A/us}$		58		$\text{nC}$

A. The value of  $R_{\text{gJA}}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The Power dissipation  $P_{\text{DSM}}$  is based on  $R_{\text{gJA}} \leq 10\text{s}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.

B. The power dissipation  $P_D$  is based on  $T_{J(\text{MAX})}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C. Single pulse width limited by junction temperature  $T_{J(\text{MAX})}=150^\circ\text{C}$ .

D. The  $R_{\text{gJA}}$  is the sum of the thermal impedance from junction to case  $R_{\text{gJC}}$  and case to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using <300 $\mu\text{s}$  pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(\text{MAX})}=150^\circ\text{C}$ . The SOA curve provides a single pulse rating.

G. The maximum current rating is package limited.



## ■ Typical Performance Characteristics

Fig 1: Output Characteristics

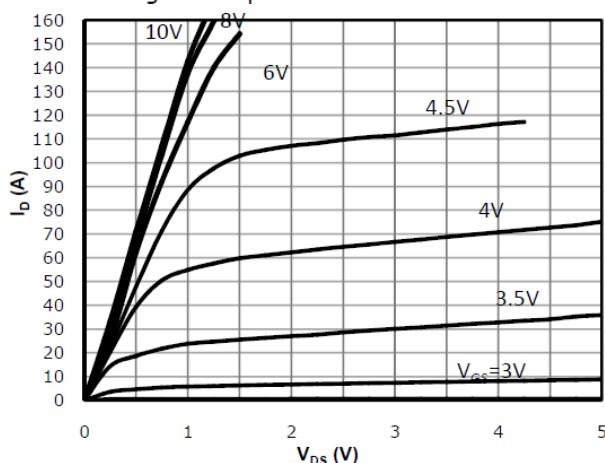


Fig 2: Transfer Characteristics

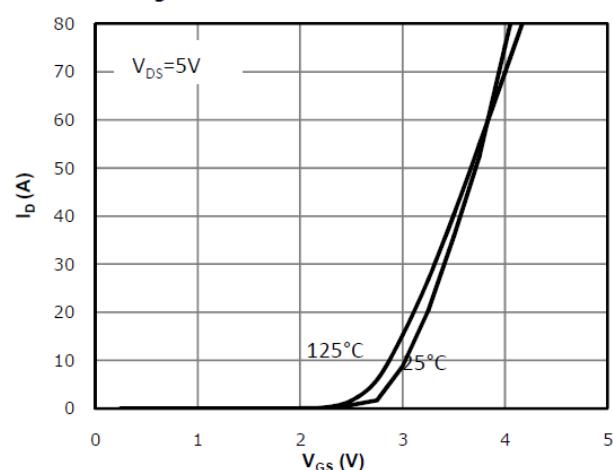
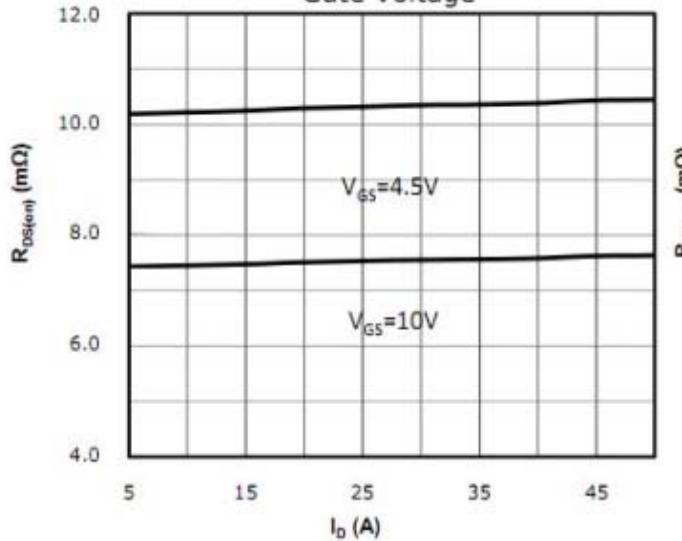
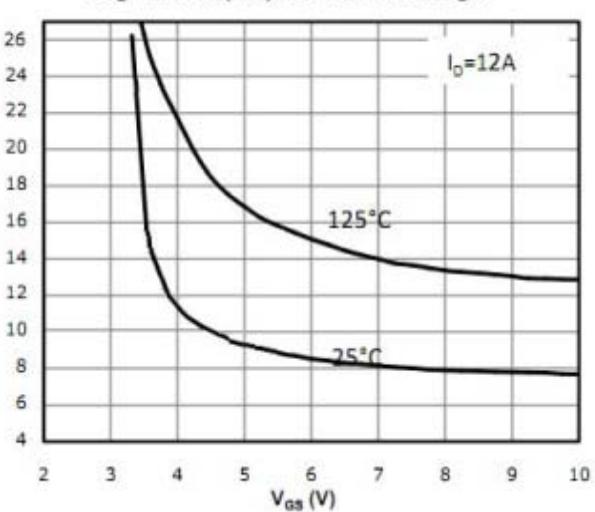
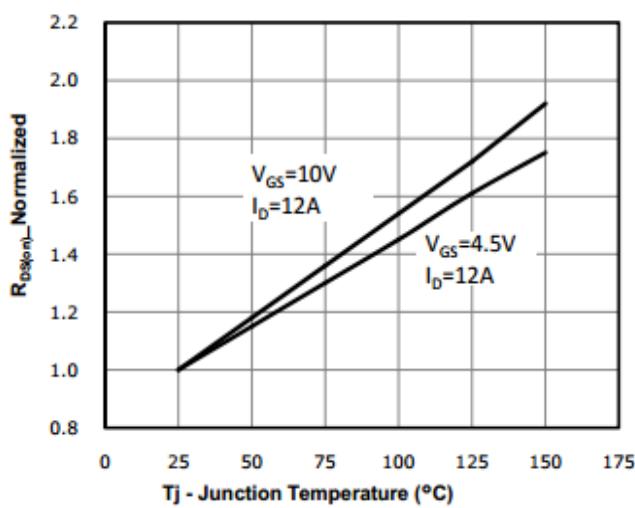
Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate VoltageFig 4:  $R_{DS(on)}$  vs Gate VoltageFig 5:  $R_{DS(on)}$  vs. Temperature

Fig 6: Capacitance Characteristics

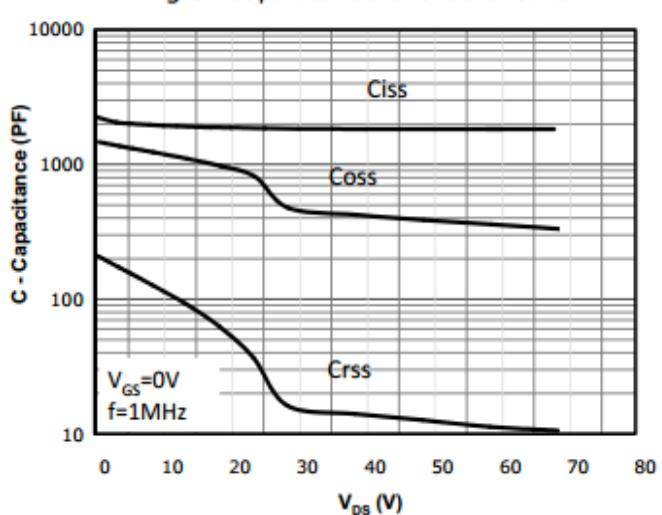




Fig 7: Gate Charge Characteristics

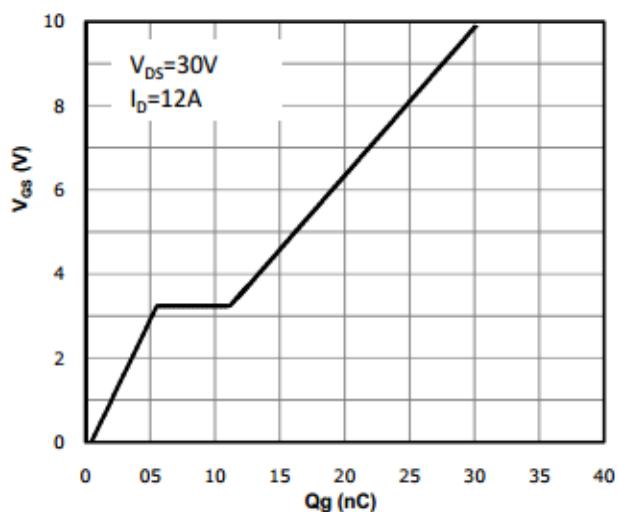


Fig 8: Body-diode Forward Characteristics

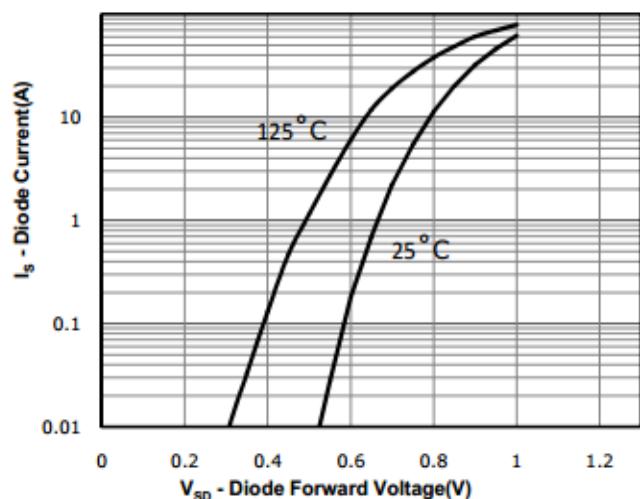


Fig 9: Power Dissipation

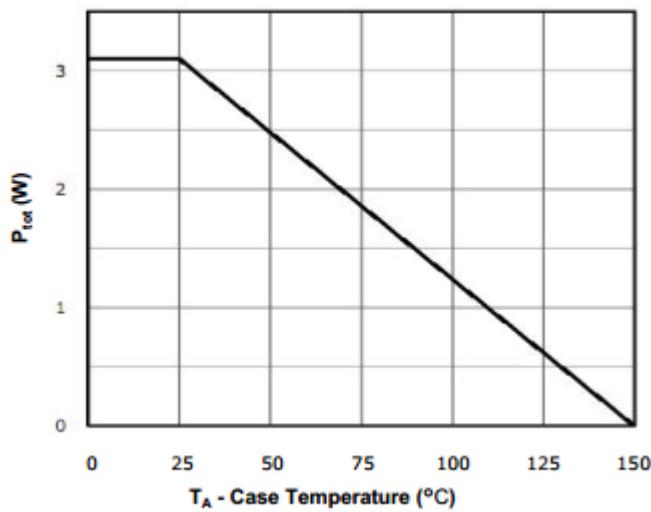


Fig 10: Drain Current Derating

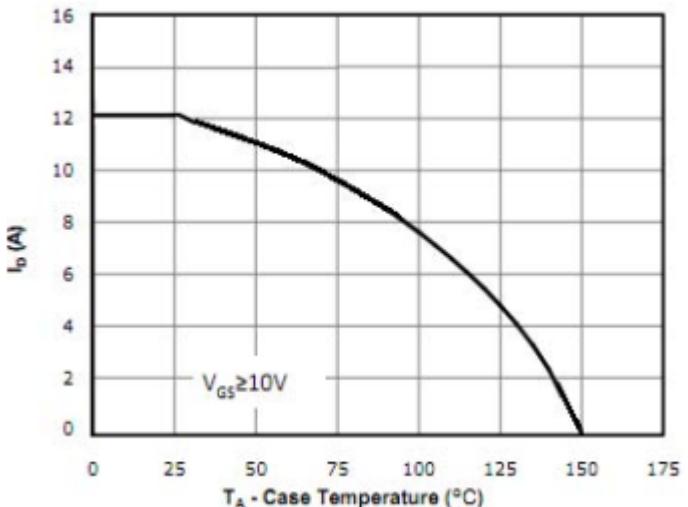




Figure A: Gate Charge Test Circuit &amp; Waveforms

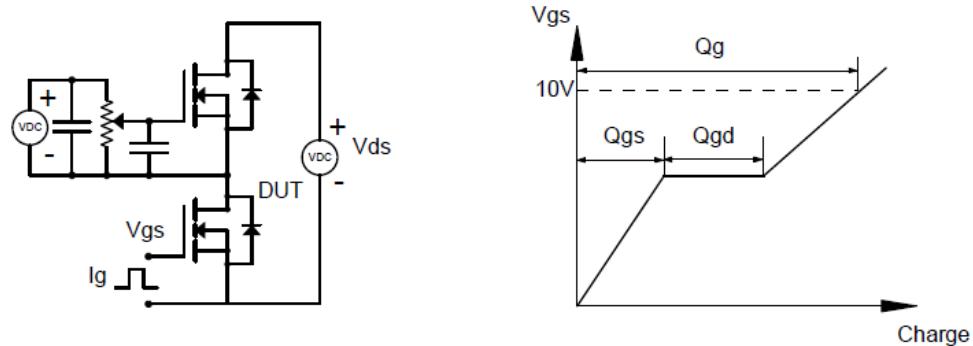


Figure B: Resistive Switching Test Circuit &amp; Waveforms

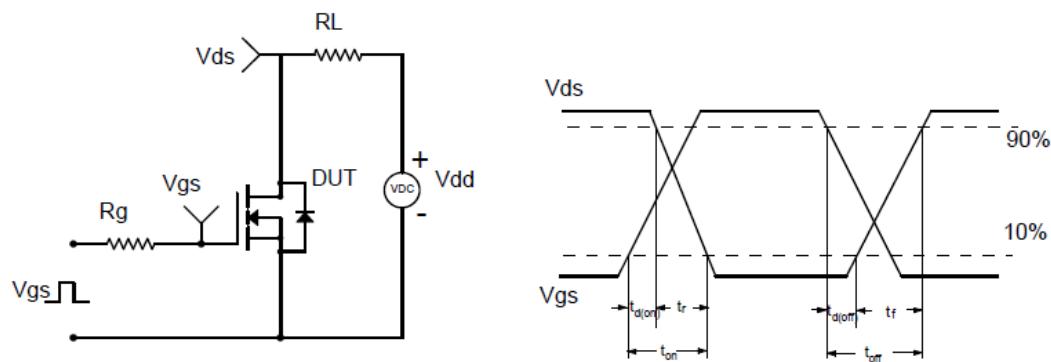


Figure C: Unclamped Inductive Switching (UIS) Test

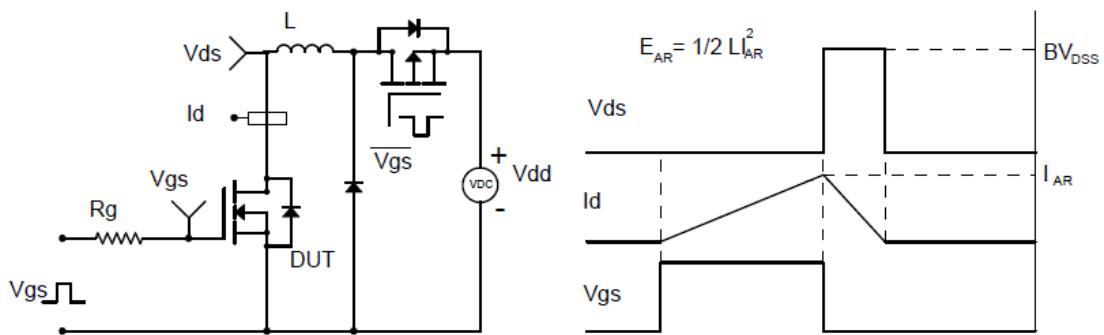
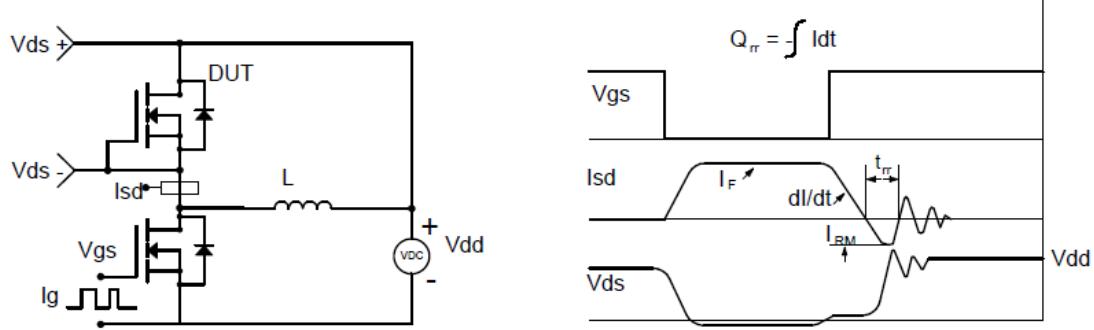
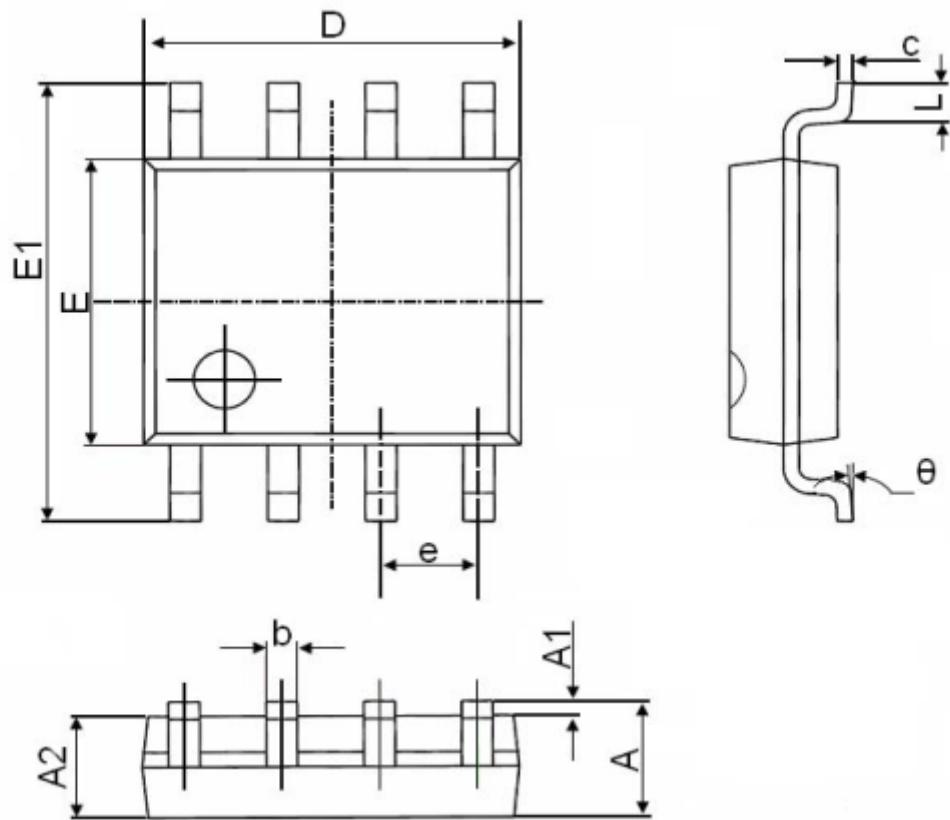


Figure D: Diode Recovery Test Circuit &amp; Waveforms





## ■SOP-8 Package information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



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